LR A67F

SIDELED®





Applications

- Cluster, Button Backlighting
- Electronic Equipment

Interior Illumination (e.g. Ambient Map)

Features:

- Package: white SMT package, colorless clear resin
- Chip technology: Thinfilm
- Typ. Radiation: 120° (Lambertian emitter)
- − Color: λ_{dom} = 625 nm (• red)
- Corrosion Robustness Class: 3B
- Qualifications: The product qualification test plan is based on the guidelines of AEC-Q101-REV-C, Stress Test Qualification for Automotive Grade Discrete Semiconductors.
- ESD: 2 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)



Ordering Information		
Туре	Luminous Intensity $^{1)}$ $I_F = 30 \text{ mA}$ I_V	Ordering Code
LR A67F-U2BB-1-1	560 2800 mcd	Q65112A9481



LR A67F

Maximum Ratings			
Parameter	Symbol		Values
Operating Temperature	T _{op}	min. max.	-40 °C 100 °C
Storage Temperature	T_{stg}	min. max.	-40 °C 100 °C
Junction Temperature	T _j	max.	125 °C
Forward current T _S = 25 °C	I _F	max.	50 mA
Surge Current t \leq 10 μ s; D = 0.005 ; T _s = 25 °C	I _{FS}	max.	100 mA
Reverse voltage ²⁾ T _S = 25 °C	V_R	max.	12 V
ESD withstand voltage acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)	V_{ESD}		2 kV



Characteristics

 $I_F = 30$ mA; $T_S = 25$ °C

Parameter	Symbol		Values
Peak Wavelength	$\lambda_{\sf peak}$	typ.	634 nm
Dominant Wavelength 3)	λ_{dom}	min.	620 nm
I _F = 30 mA	33	typ.	625 nm
		max.	629 nm
Spectral Bandwidth at 50% I _{rel,max}	Δλ	typ.	16 nm
Viewing angle at 50% $\rm I_{v}$	2φ	typ.	120 °
Forward Voltage 4)	V_{F}	min.	1.80 V
I _F = 30 mA	·	typ.	2.00 V
		max.	2.40 V
Reverse current ²⁾	I _R	typ.	0.01 µA
$V_R = 12 \text{ V}$		max.	10 µA
Temperature Coefficient of Peak Wavelength -10°C ≤ T ≤ 100°C	$TC_{\lambda peak}$	typ.	0.14 nm / K
Temperature Coefficient of Dominant Wavelength -10°C ≤ T ≤ 100°C	$TC_{\lambda dom}$	typ.	0.07 nm / K
Real thermal resistance junction/solderpoint 5)	$R_{ ext{thJS real}}$	max.	180 K / W



Brightness Groups

Group	Luminous Intensity ¹⁾ $I_F = 30 \text{ mA}$ min. I_V	Luminous Intensity. 1) I _F = 30 mA max. I _v	Luminous Flux $^{6)}$ I _F = 30 mA typ. Φ_{V}
U2	560 mcd	710 mcd	1910 mlm
V1	710 mcd	900 mcd	2420 mlm
V2	900 mcd	1120 mcd	3030 mlm
AA	1120 mcd	1400 mcd	3780 mlm
AB	1400 mcd	1800 mcd	4800 mlm
BA	1800 mcd	2240 mcd	6060 mlm
ВВ	2240 mcd	2800 mcd	7560 mlm

Forward Voltage Groups

Group	Forward Voltage ⁴⁾ I _F = 30 mA min. V _F	Forward Voltage ⁴⁾ I _F = 30 mA max. V _F	
E3	1.80 V	1.95 V	
H3	1.95 V	2.10 V	
L3	2.10 V	2.25 V	
P3	2.25 V	2.40 V	



Group Name on Label

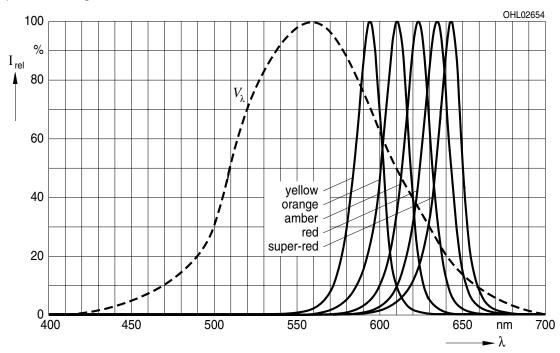
Example: AA-1-E3

Brightness	Wavelength	Forward Voltage
AA	1	E3



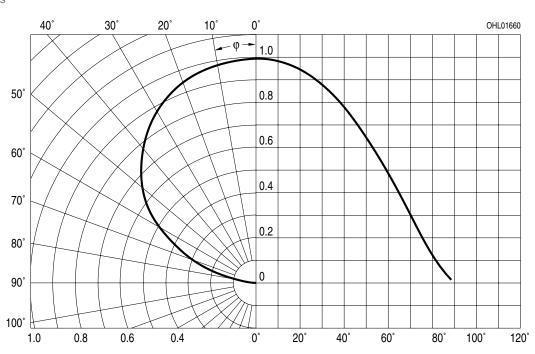
Relative Spectral Emission 6)

$$I_{rel} = f(\lambda); I_F = 30 \text{ mA}; T_S = 25 ^{\circ}\text{C}$$



Radiation Characteristics 6)

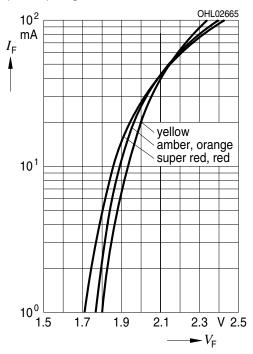
$$I_{rel} = f(\phi); T_S = 25 °C$$





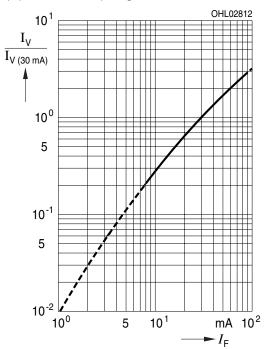
Forward current 6), 7)

$$I_F = f(V_F); T_S = 25 \text{ }^{\circ}\text{C}$$



Relative Luminous Intensity 6), 7)

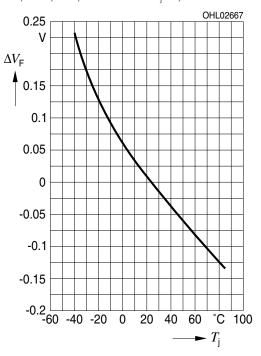
$$I_{v}/I_{v}(30 \text{ mA}) = f(I_{F}); T_{S} = 25 \text{ °C}$$





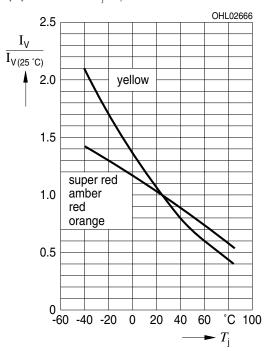
Forward Voltage 6)

$$\Delta V_{_F} = V_{_F} - V_{_F} (25~^{\circ}\text{C}) = f(T_{_j});~ I_{_F} = 30~\text{mA}$$



Relative Luminous Intensity 6)

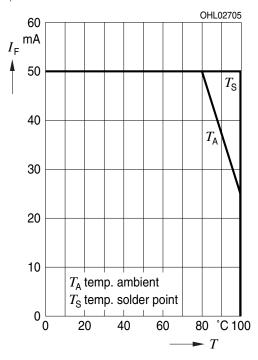
$$I_{v}/I_{v}(25 \text{ °C}) = f(T_{j}); I_{F} = 30 \text{ mA}$$





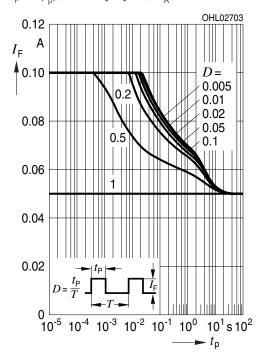
Max. Permissible Forward Current

$$I_{F} = f(T)$$



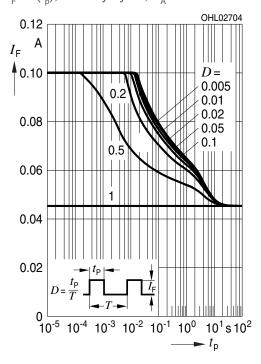
Permissible Pulse Handling Capability

$I_{_{\rm F}}$ = f(t $_{_{\rm p}}$); D: Duty cycle; $T_{_{\rm A}}$ = 25 °C

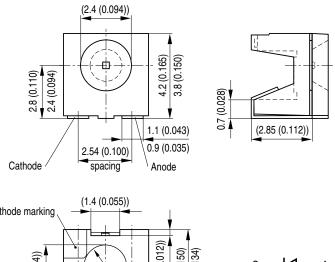


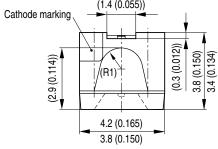
Permissible Pulse Handling Capability

$$I_F = f(t_p)$$
; D: Duty cycle; $T_A = 85 \, ^{\circ}C$



Dimensional Drawing 8)







GPLY6880

Further Information:

Approximate Weight: 67.0 mg

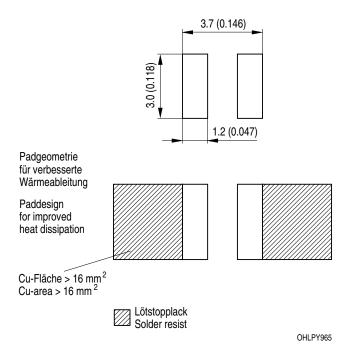
Package marking: Cathode

Corrosion test: Class: 3B

Test condition: 40°C / 90 % RH / 15 ppm H₂S / 14 days (stricter than IEC

60068-2-43)

Recommended Solder Pad 8)

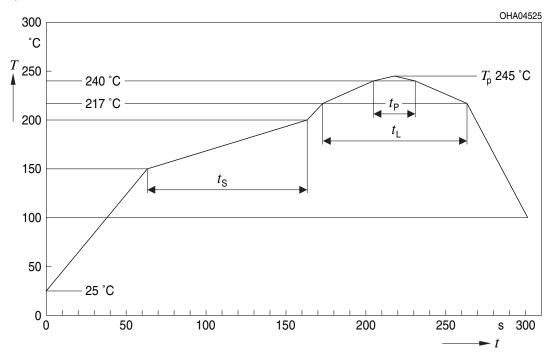


For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere. Package not suitable for ultra sonic cleaning.



Reflow Soldering Profile

Product complies to MSL Level 2 acc. to JEDEC J-STD-020E



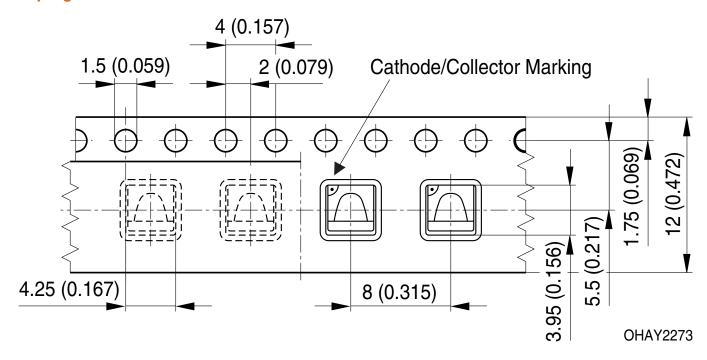
Profile Feature	Symbol	Symbol Pb-Free (SnAgCu) Assembly			
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat*)	'		2	3	K/s
25 °C to 150 °C					
Time t _s	t _s	60	100	120	S
T_{Smin} to T_{Smax}					
Ramp-up rate to peak*)			2	3	K/s
T_{Smax} to T_{P}					
Liquidus temperature	T_L		217		°C
Time above liquidus temperature	$t_{\scriptscriptstyle L}$		80	100	S
Peak temperature	T_{P}		245	250	°C
Time within 5 °C of the specified peak	t _P	10	20	30	S
temperature T _P - 5 K					
Ramp-down rate*			3	4	K/s
T _P to 100 °C					
Time				480	S
25 °C to T _P					

All temperatures refer to the center of the package, measured on the top of the component



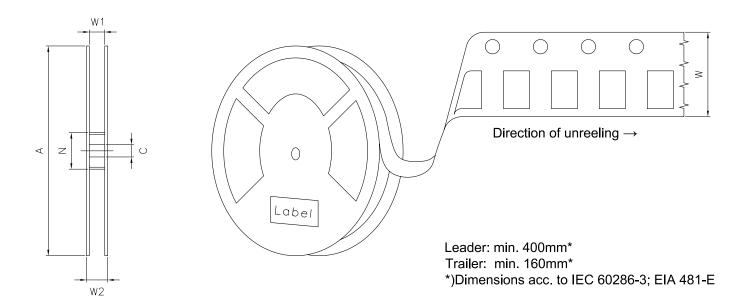
^{*} slope calculation DT/Dt: Dt max. 5 s; fulfillment for the whole T-range

Taping 8)





Tape and Reel 9)

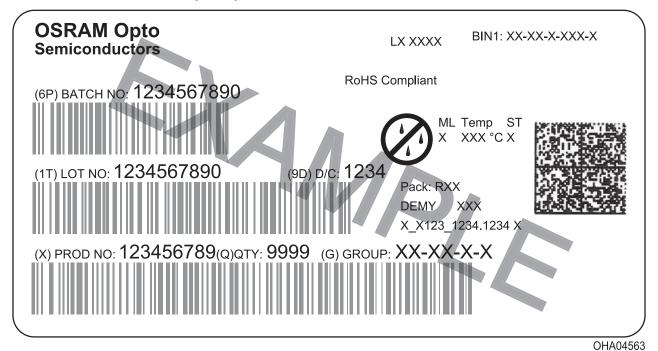


Reel Dimensions

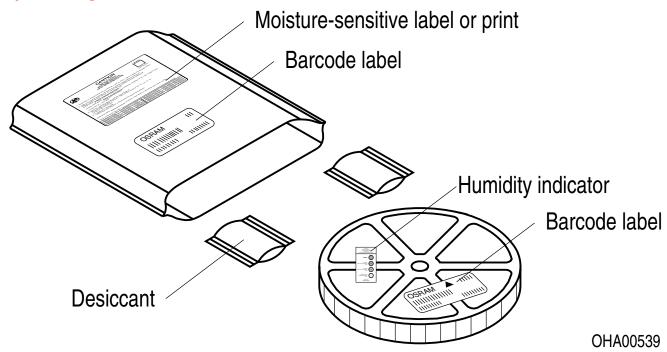
Α	W	N_{\min}	W ₁	W_{2max}	Pieces per PU
330 mm	12 + 0.3 / - 0.1 mm	60 mm	12.4 + 2 mm	18.4 mm	2000



Barcode-Product-Label (BPL)



Dry Packing Process and Materials 8)



Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.



Type Designation System

Wavele (λ _{dom} ty		Emission Co		or coordinates 1931/Emission		
A : 6 S : 6	, 17 nm 33 nm	amber super red	W: UW			
	28 nm	true green	CB:			
_	87 nm 06 nm	yellow orange	CG: CL:			
	70 nm	green	OL.	color on dem	and laguine	
	60 nm	pure green			_	
	25 nm	red		Package		
	70 nm	blue		A: SIE	ELED	
_	45 nm 05 nm	hyper-red verde green/	/ /			
•••	00 11111	7				
L: L	ight /	/				
e	mitting /					
d	iode /					
L	A		A	6	7	6
Loa	d / Backar	no Proportios				
6:	folded l	ge Properties eads				
	Encan	sulant Type / L	one Prone	ortios		
				lume conversio	n/	
		(resin encapsula	ation)			
	S:	Silicone (with or	without di	ffuser) /	(
		echnology:				
		indard InGaN				
		andard InGalP OP 2000				
	C: AT					
		infilm InGaAIP				
				ubcon:Sapphire) /	
	K: Inc	GaAIP low curre	nt			
				/	1	



Notes

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet fall into the class **exempt group (exposure time 10000 s)**. Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use. Devices that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related information please visit www.osram-os.com/appnotes



Disclaimer

Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version on the OSRAM OS website.

Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

Product and functional safety devices/applications or medical devices/applications

OSRAM OS components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.

OSRAM OS products are not qualified at module and system level for such application.

In case buyer – or customer supplied by buyer – considers using OSRAM OS components in product safety devices/applications or medical devices/applications, buyer and/or customer has to inform the local sales partner of OSRAM OS immediately and OSRAM OS and buyer and /or customer will analyze and coordinate the customer-specific request between OSRAM OS and buyer and/or customer.



Glossary

- Brightness: Brightness values are measured during a current pulse of typically 25 ms, with an internal reproducibility of ± 8 % and an expanded uncertainty of ± 11 % (acc. to GUM with a coverage factor of k = 3).
- Reverse Operation: This product is intended to be operated applying a forward current within the specified range. Applying any continuous reverse bias or forward bias below the voltage range of light emission shall be avoided because it may cause migration which can change the electro-optical characteristics or damage the LED.
- Wavelength: The wavelength is measured at a current pulse of typically 25 ms, with an internal reproducibility of ±0.5 nm and an expanded uncertainty of ±1 nm (acc. to GUM with a coverage factor of k = 3).
- Forward Voltage: The forward voltage is measured during a current pulse of typically 8 ms, with an internal reproducibility of ± 0.05 V and an expanded uncertainty of ± 0.1 V (acc. to GUM with a coverage factor of k = 3).
- Thermal Resistance: Rth max is based on statistic values (6σ) .
- Typical Values: Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- Characteristic curve: In the range where the line of the graph is broken, you must expect higher differences between single devices within one packing unit.
- Tolerance of Measure: Unless otherwise noted in drawing, tolerances are specified with ±0.1 and dimensions are specified in mm.
- ⁹⁾ **Tape and Reel:** All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.



LR A67F

Revision	Revision History				
Version	Date	Change			
1.6	2019-10-17	Ordering Information Brightness Groups			
1.7	2021-02-10	Features Schematic Transportation Box Dimensions of Transportation Box Glossary			
1.8	2021-04-28	Features			



Published by OSRAM Opto Semiconductors GmbH EU RoHS and China RoHS compliant product Leibnizstraße 4, D-93055 Regensburg www.osram-os.com © All Rights Reserved.

此产品符合欧盟 RoHS 指令的要求; 按照中国的相关法规和标准,不含有毒有害物质或元素。



